IGBT - Shorted-Anode

1300 V, 30 A

FGH30S130P

Description

Using advanced field stop trench and shorted-anode technology, ON Semiconductor's shorted-anode trench IGBTs offer superior conduction and switching performances for soft switching applications. The device can operate in parallel configuration with exceptional avalanche capability. This device is designed for induction heating and microwave oven.

Features

- High Speed Switching
- Low Saturation Voltage: $V_{CE(sat)} = 1.75 \text{ V}$ @ $I_C = 30 \text{ A}$
- High Input Impedance
- This Device is Pb-Free and is RoHS Compliant

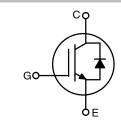
Applications

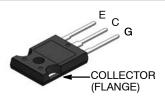
• Induction Heating, Microwave Oven



ON Semiconductor®

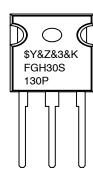
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TO-247-3LD CASE 340CK

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code

&K = Lot Code

1

FGH30S130P = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Descrip	Symbol	Rating	Unit	
Collector to Emitter Voltage Gate to Emitter Voltage		V _{CES}	1300	V
		V _{GES}	±25	V
Collector Current T _C = 25°C		I _C	60	Α
Collector Current T _C = 100°C		1	30	А
Pulsed Collector Current (Note 1)	I _{CM}	90	А	
Diode Continuous Forward Current $T_C = 25^{\circ}C$		I _F	60	Α
Diode Continuous Forward Current $T_C = 100^{\circ}C$		1	30	Α
Maximum Power Dissipation $T_C = 25^{\circ}C$		P _D	500	W
Maximum Power Dissipation T _C = 100°C		1	250	W
Operating Junction Temperature		TJ	-55 to +175	°C
Storage Temperature Range	T _{stg}	-55 to +175	°C	
Maximum Lead Temp. for soldering Purpo	TL	300	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Limited by Tjmax.

THERMAL CHARACTERISTICS

Parameter	Symbol	Тур	Max	Unit
Thermal Resistance, Junction to Case, Max	$R_{\theta JC}$ (IGBT)	-	0.3	°C/W
Thermal Resistance, Junction to Ambient, Max	$R_{ hetaJA}$	-	40	°C/W

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Mark	Package	Reel Size	Tape Width	Quantity
FGH30S130P	FGH30S130P	TO-247	-	-	30

ELECTRICAL CHARACTERISTICS OF THE IGBT ($T_C = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS		•				-
Collector Cut-Off Current	I _{CES}	V _{CE} = 1300, V _{GE} = 0 V	_	_	1	mA
G-E Leakage Current	I _{GES}	V _{GE} = V _{GES} , V _{CE} = 0 V	-	_	±500	nA
ON CHARACTERISTICs						
G-E Threshold Voltage	$V_{GE(th)}$	I_C = 30 mA, V_{CE} = V_{GE}	4.5	6.0	7.5	V
Collector to Emitter Saturation Voltage	V _{CE(sat)}	I _C = 30 A, V _{GE} = 15 V, T _C = 25°C	-	1.75	2.3	V
		I _C = 30 A, V _{GE} = 15 V, T _C = 125°C	-	1.85	-	V
		I _C = 30 A, V _{GE} = 15 V, T _C = 175°C	-	1.9	-	V
Diode Forward Voltage	V_{FM}	I _F = 30 A, T _C = 25°C	-	1.7	2.2	V
		I _F = 30 A, T _C = 175°C	-	2.1	-	V

ELECTRICAL CHARACTERISTICS OF THE IGBT (T_C = 25°C unless otherwise noted) (continued)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{ies}	V _{CE} = 30 V, V _{GE} = 0 V, f = 1 MHz	_	3345	_	pF
Output Capacitance	C _{oes}		=	75	-	pF
Reverse Transfer Capacitance	C _{res}		_	60	-	pF
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(on)}	V _{CC} = 600 V, I _C = 30 A,	_	39	_	ns
Rise Time	t _r	$R_G = 10 \Omega$, $V_{GE} = 15 V$, Resistive Load, $T_C = 25^{\circ}C$	_	360	_	ns
Turn-Off Delay Time	t _{d(off)}		_	620	-	ns
Fall Time	t _f		_	160	210	ns
Turn-On Switching Loss	E _{on}	7	-	1.3	-	mJ
Turn-Off Switching Loss	E _{off}	7	_	1.22	1.6	mJ
Total Switching Loss	E _{ts}	1		2.52	_	mJ
Turn-On Delay Time	t _{d(on)}	$V_{CC} = 600 \text{ V, } I_{C} = 30 \text{ A,}$ $R_{G} = 10 \Omega, V_{GE} = 15 \text{ V,}$ Resistive Load, $T_{C} = 175^{\circ}\text{C}$	-	38	-	ns
Rise Time	t _r		-	375	-	ns
Turn-Off Delay Time	t _{d(off)}		_	635	_	ns
Fall Time	t _f		_	270	_	ns
Turn-On Switching Loss	E _{on}	7	_	1.59	_	mJ
Turn-Off Switching Loss	E _{off}		_	1.78	_	mJ
Total Switching Loss	E _{ts}		_	3.37	_	mJ
Total Gate Charge	Qg	V _{CE} = 600 V, I _C = 30 A, V _{GE} = 15 V	_	372.3	_	nC
Gate to Emitter Charge	Q _{ge}		_	18.7	_	nC
Gate to Collector Charge	Q _{gc}	1	-	156.2	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL PERFORMANCE CHARACTERISTICS

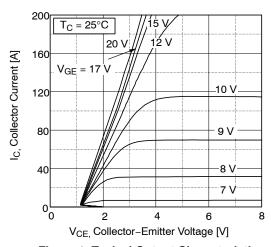


Figure 1. Typical Output Characteristics

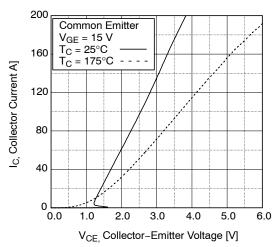


Figure 3. Typical Saturation Voltage Characteristics

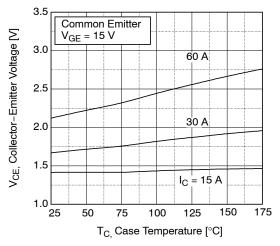


Figure 5. Saturation Voltage vs. Case Temperature at Variant Current Level

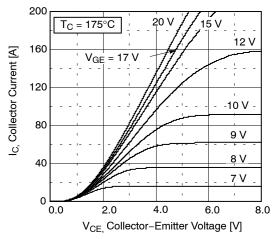


Figure 2. Typical Output Characteristics

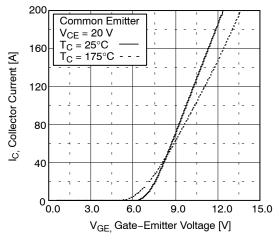


Figure 4. Transfer Characteristics

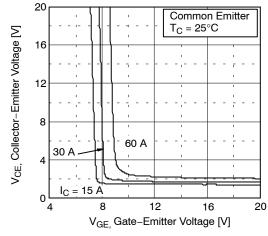


Figure 6. Saturation Voltage vs. V_{GE}

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

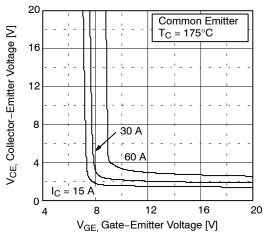
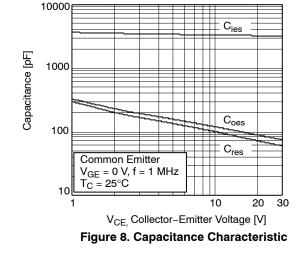


Figure 7. Saturation Voltage vs. V_{GE}



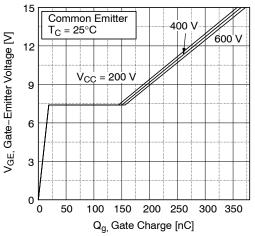


Figure 9. Gate Charge Characteristics

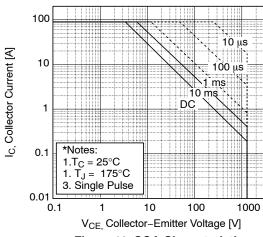


Figure 10. SOA Characteristics

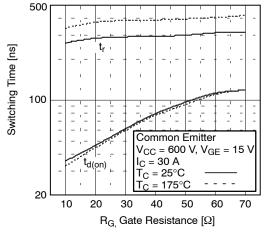


Figure 11. Turn-On Characteristics vs. Gate Resistance

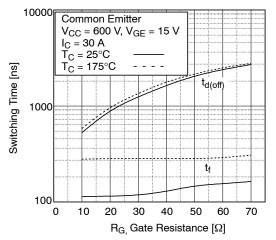


Figure 12. Turn-Off Characteristics vs. Gate Resistance

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

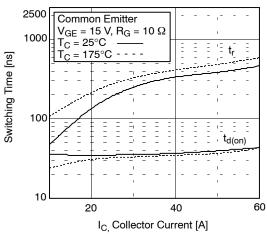


Figure 13. Turn-On Characteristics vs. Collector Current

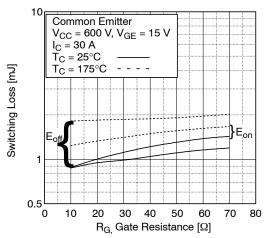


Figure 15. Switching Loss vs. Gate Resistance

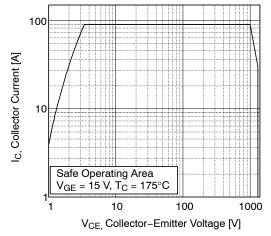


Figure 17. Turn-Off Switching SOA Characteristics

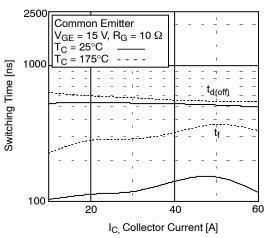


Figure 14. Turn-Off Characteristics vs. Collector Current

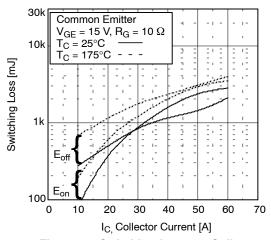


Figure 16. Switching Loss vs. Collector Current

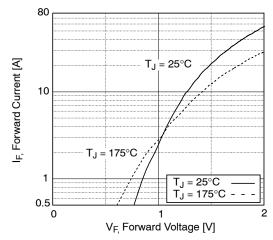


Figure 18. Forward Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (continued)

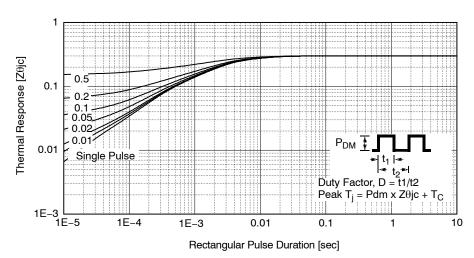
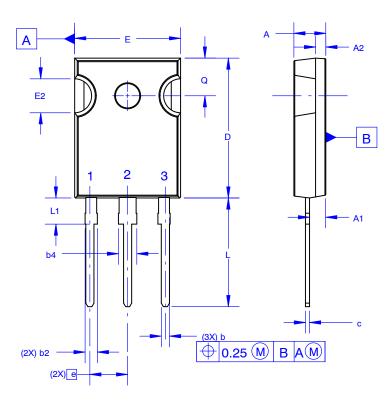


Figure 19. Transient Thermal Impedance of IGBT

TO-247-3LD SHORT LEAD

CASE 340CK ISSUE A





- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
- D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

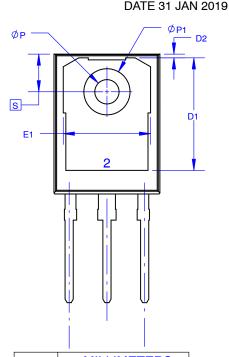
A = Assembly Location

Y = Year

WW = Work Week

ZZ = Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.



DIM	MILLIMETERS				
DIIVI	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A 1	2.20	2.40	2.60		
A2	1.40	1.50	1.60		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
b4	2.42	2.54	2.66		
С	0.51	0.61	0.71		
D	20.32	20.57	20.82		
D1	13.08	~	~		
D2	0.51	0.93	1.35		
E	15.37	15.62	15.87		
E1	12.81	?	~		
E2	4.96	5.08	5.20		
е	~	5.56	~		
L	15.75	16.00	16.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
ØP1	6.60	6.80	7.00		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		

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DESCRIPTION:	TO-247-3LD SHORT LEAD		PAGE 1 OF 1	

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 TIG058E8-TL-H
 VS-CPV364M4KPBF
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 NGTG40N120FL2WG
 RJH60F3DPQ-A0#T0

 APT40GR120B2SCD10
 APT15GT120BRG
 APT20GT60BRG
 NGTB75N65FL2WAG
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 IGW08T120FKSA1
 IGW75N60H3FKSA1
 HGTG40N60B3
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 FGH75T65UPD
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 IDW40E65D2FKSA1